

THCOM The Coordinated-Team

HIGH SPEED LAN 10/100BASE-TX MAGNETIC MODULE(SMD)

Feature:

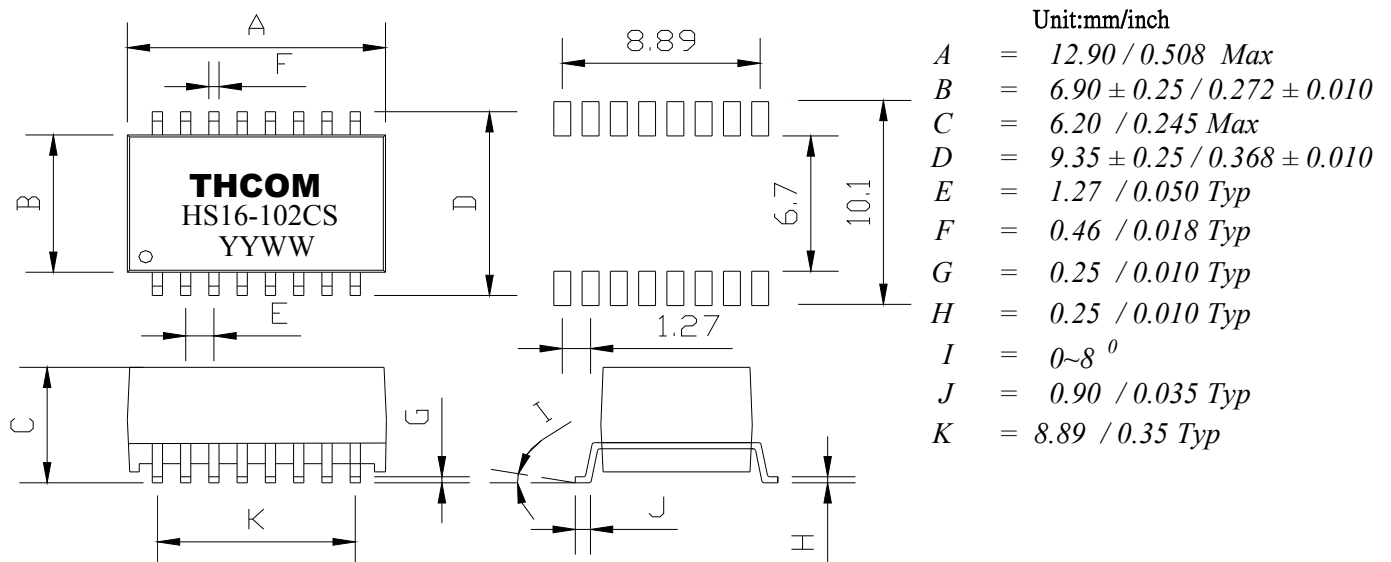
- M** Operating Temperature -40 °C To 85 °C
- M** Designed To Meet IEEE802.3, ANSI X3.263 Standards
- M** 16 PIN SMT Designed For Reflow Soldering Temperatures Up To 245 °C
- M** Low Leakage Inductance And Winding Capacitances of Fast Rise Time High Isolation Voltages To Comply With International Safety.
- M** Requirement For LAN .
- M** Half Port and Single Port Designs for Maximum Layout Flexibility.
- M** Compatible With INTEL ,TDK,QSI and Lcs Transiversce.
- M** For ROHS Part add postfix G.
- T** Isolation Voltage :1500Vrms.

ELECTRICAL CHARACTERISTICS @25 °C

Rise Time & Fall Time @ 5.0nS(Max),Isolation Hi-pot:1500Vrms(pri/sec),Pri.OCL:TX&RX:350uH Min@Idc=8mA

Part Number	Insertion Loss (dB Max)	Return Loss (dB Min)				Common Mode Rejection Ratio (dB Min)			Cross Talk (dB Min)		Cw/w (Pf)	DC Resistanc (Ω Max)	Turn Ratio TX/RX (±5%)
		1-30	40	50	60-80	1-30	60	80-100	1-30	60-100			
		MHz	MHz	MHz	MHz	MHz	MHz	MHz	MHz	MHz			
HS16-102CS	-1.1	-18	-16	-14.5	-12	-40	-35	-30	-42	-35	15	0.9	1CT:1/1CT:1CT

Dimensions:



Unless otherwise specified, all tolerances are mm(inch) ± 0.25(0.010)

Schematic:

